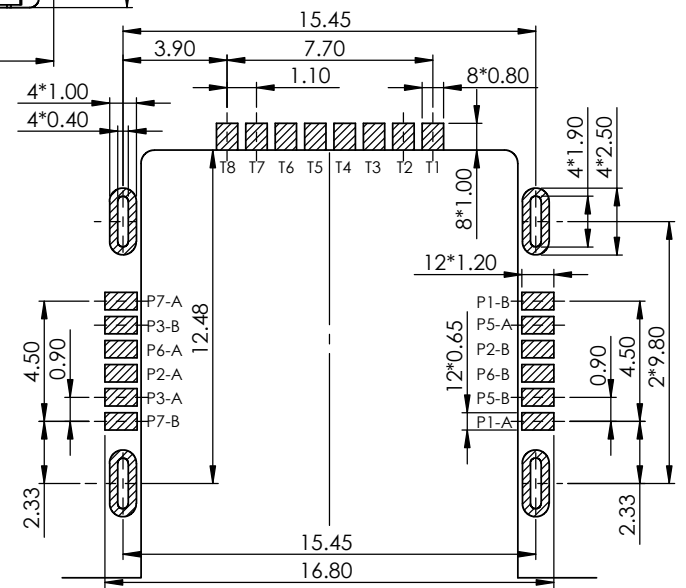


NOTES:  
 1.MATERIAL:  
 HOUSING:LCP, BLACK, UL 94V-0  
 CONTACT:PHOSPHORBRONZE,T=0.15MM  
 SHELL:STAINLESS STEEL T=0.15MM  
 2.FINISH  
 CONTACT: 50U" MIN PLATING OVER ALL  
 GOLD FLASH ON THE CONTACT AREA AND SOLDER AREA  
 SHELL:SELECTIVE GOLD FLASH IN SOLDER TAIL AREA  
 50U" NI MIN. PLATING OVER ALL  
 3.ALL DIMENSIONS MARKED (X) MUST BE CONTROLLED BY QC  
 ALL DIMENSIONS MARKED (XX) MUST BE MEASURED BY FAI  
 4.RATED PARAMETERS OF CONNECTOR  
 4-1.Operating temperature: -40°C to 70°C  
 4-2.Rated Current: 0.5A  
 4-3.Rated Voltage: 30V DC Per Contact  
 5.ELECTRICAL MECHANICAL ENVIRONMENTAL  
 5-1.Dielectric withstanding Voltage: 500V AC 1min.  
 5-2.Insulation Resistance: 1000 MΩMin.  
 5-3.Normal Force: 50g Min. Per Pin  
 5-4.Durability: 3000 cycles  
 5-5.Contact Resistance: 50mΩ MAX.



SIM CARD PIN NO.	PIN NO.	T-CARD PIN NO.	PIN NO.
P1-A/B	VCC	T1	DAT2
P2-A/B	RST	T2	CD/DAT3
P3-A/B	CLK	T3	CMD
P5-A/B	GND	T4	VDD
P6-A/B	VPP	T5	CLK
P7-A/B	I/O	T6	VSS
		T7	DAT0
		T8	DAT1

REV.	ECN NO.	DESCRIPTION	DATE	REV.	UNITS: mm	SCALE: 5/1	SHEET: 1/1	FINISH: SEE NOTE
E	E1609368A	接触点移位0.35mm 兼容小芯片卡片	09/03'2016	A				
D	E1412381A	改善抽屜不易拉出	12/23'2014					
C	E1412370A	设定大小弹高 预防短路风险	12/19'2014					
B	E1411289A	塑胶加胶 弹高设定	12/01'2014					

GENERAL TOLERANCE	DRAW:	PART NO:
X. ±0.30 X' ±0.20 .XX ±0.10 .XXX ±0.05		S78-0B23F38A
X." ±2.00 .X' ±1.00 .XX" ±0.50 .XXX' ±0.10	CHECKED:	TITLE: SIM CARD&MICRO SIM CARD &TF CARD 成品H=3.80mm,板上2.30
	APPROVE:	DRAWING NO:



昆山捷皇电子精密科技有限公司  
 HONGRIDA ELECTRONIC TECHNOLOGY CO., LTD.